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FORM COVER SHEET

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09/091081

ks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):  
**Viktor Anatolievich IOVDALSKY**  
**Jury Isaevich MOLDOVANOV**

Additional names(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other: \_\_\_\_\_

Execution Date: **October 29, 1996**

2. Name and address of receiving party(ies):

Name: **Samsung Electronics Co. Ltd.**

Address: **416, Maetan-3 Dong**

**Paldal-Ku**

City: **Suwon City, Gyungki-Do** State/Prov.: \_\_\_\_\_

Country: **Republic of Korea** ZIP: \_\_\_\_\_

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or registration numbers(s):

09691681

If this document is being filed together with a new application, the execution date of the application is: **June 10, 1998**

Patent Application No. \_\_\_\_\_

Filing date \_\_\_\_\_

B. Patent No.(s) \_\_\_\_\_

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **William T. Rifkin**

Registration No. **26501**

Address: **RUDNICK & WOLFE**

**P.O. Box 64807**

City: **Chicago** State/Prov.: **IL**

Country: **USA** ZIP: **60664-0807**

6. Total number of applications and patents involved: **1**

7. Total fee (37 CFR 3.41):.....\$ **40.00**

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account

☐ Authorized to be charged to deposit account

8. Deposit account number:

**18-2284**

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

**William T. Rifkin, Esq.**

Name of Person Signing

Signature

**June 10, 1998**

Date

Total number of pages including cover sheet, attachments, and document:

**3**

PATENT

REEL: 010080 FRAME: 0059

This assignment agreement is applicable to the invention entitled (Invention Title) \_\_\_\_\_

High Power Microwave Integrated Circuit

The PATENT RIGHTS referred to in this agreement are:

- (check one) ☐ a patent application for this invention, executed by the ASSIGNOR(S) concurrently with this assignment.
- ☐ U.S. patent application Serial No. \_\_\_\_\_, filed \_\_\_\_\_
- ☒ a U.S. patent application based on PCT International Application No. PCT/RU 96/ 00288 filed on (date) 10.10.96 (U.S. patent application Serial No. \_\_\_\_\_, if known).
- ☐ U.S. patent No. \_\_\_\_\_, issued \_\_\_\_\_

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

- (check one) ☐ U.S. patent rights only.
- ☒ Worldwide patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date of any U.S. or foreign patent application for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) Samsung Electronics Co. Ltd

Address) 416, Maetan-3 Dong, Paldal-Ku, Suwon City, Gyungki-Do,  
Republic of Korea

The ASSIGNEE is:

- (check one) ☐ An Individual.
- ☐ A Partnership.
- ☒ A Corporation of Republic of Korea (specify state or country)
- ☐ (other) \_\_\_\_\_

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, hereby assign(s) the following rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and,

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable provisions, based on any earlier patent applications for this invention.

ASSIGNEE: Samsung Electronics Co., Ltd.

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any facts known to the ASSIGNOR(S) respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause any and all Letters Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNORS authorize any attorneys and agents who have a power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Name of sole or first inventor

Signature

22.10.16c.  
Date ..

Name of second inventor, if any

Signature

Date 29.10.96

me of third inventor, if any

Signature

Date

Name of fourth inventor, if any

Signature

Date \_\_\_\_\_

Name of fifth inventor, if any

Signature

Date \_\_\_\_\_

Name of sixth inventor, if any

Signature

Date \_\_\_\_\_

Name of seventh inventor, if any

Signature

Date \_\_\_\_\_

Name of eighth inventor, if any

Signature

Date \_\_\_\_\_

Name of ninth inventor, if any

Signature \_\_\_\_\_

Date \_\_\_\_\_